

Current session 10/09/2004

(C) QUESTEL 1994

QUESTEL.ORBIT (TM) 1998

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Query/Command : FILE PLUSPAT

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Selected file: PLUSPAT

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Last update of file: 2004/09/08 (YYYY/MM/DD) 2004-36/UP (basic update)

Search statement : 1

Query/Command : US6132851/PN

** SS 1: Results 1

Search statement : 2

Query/Command : PRT FULL NONSTOP LEGALALL

1/1 PLUSPAT - ©QUESTEL-ORBIT

- PN** - US6132851 A 20001017 [US6132851]
- TI** - (A) Adhesive compositions and copper foils and copper clad laminates using same
- PA** - (A) GA TEK INC (US)
- PA0** - GA-TEK Inc., Eastlake OH [US]
- IN** - (A) POUTASSE CHARLES A (US)
- AP** - US26787794 19940628 [1994US-0267877]
- PR** - US26787794 19940628 [1994US-0267877]
- IC** - (A) B32B-003/00
- EC** - C08G-059/02
C08G-059/06
C08G-059/40
C09J-163/00 & B4B2
H05K-003/38D
- ICO** - T05K-003/02C
T05K-003/38C
- PCL** - ORIGINAL (O) : 428209000; CROSS-REFERENCE (X) : 428408000
428413000 428417000 428418000 428446000 428457000 428901000
525109000 525113000
- DT** - Corresponding document
- CT** - US3496130; US3935053; US4020225; US4246162; US4343843; US5061550;
US5071914; EP0012714; EP0148493; EP0371242; JP62-101674
Search Report for European Appl. 95304380.9.
- Epoxy Resins, Chem. & Tech., May, 8, 1989 Marcel Dekker Inc., pp. 683-691, 1089-1095.
- STG** - (A) United States patent
- AB** - This invention relates to an adhesive composition, comprising: (A) at least one phenolic resole resin; and (B) the product made by reacting (B-1) at least one difunctional epoxy resin, with (B-2) at least one compound represented by the formula (Chemical Structure image '1' not included in text) wherein in Formulae (I) and (II): G, T and Q are each independently functional groups selected from the group consisting of COOH, OH, SH, NH₂, NHR₁, (NHC(.dbd.NH))_m NH₂, R₂ COOH, NR₁₂, C(O)NHR₁, R₂ NR₁₂, R₂ OH, R₂ SH, R₂ NH₂ and R₂ NHR₁, wherein R₁ is a hydrocarbon group, R₂ is an alkylene or alkylidene group and m is a number in the range of 1 to about 4; T can also be R₁, OR₁ or SO₂ C₆ H₄ --NH₂; and Q can also be H. The invention also relates to copper foils having the foregoing adhesive composition adhered to at least one side thereof to enhance the adhesion between said foils and dielectric substrates. The invention also relates to laminates comprising copper foil, a dielectric substrate, and an adhesion-promoting layer comprising the foregoing adhesive composition disposed between and adhered to the foil and the substrate.
- UP** - 2000-44

1 / 1 LGST - ©EPO

PN - US6132851 A 20001017 [US6132851]
AP - US26787794 19940628 [1994US-0267877]
ACT - 20000522 US/AS-A
ASSIGNMENT
OWNER: GA-TEK INC. 34929 CURTIS BOULEVARD EASTLAKE OHIO 4;
EFFECTIVE DATE: 19971030
CHANGE OF NAME;ASSIGNOR:GOULD ELECTRONICS,
INC.;REEL/FRAME:010923/0373

20031111 US/RF-A
REISSUE APPLICATION FILED
EFFECTIVE DATE: 20021017

20031118 US/RF-A
REISSUE APPLICATION FILED
EFFECTIVE DATE: 20021017

UP - 2004-29

1 / 1 CRXX - ©CLAIMS/RRX

PN - 6,132,851 A 20001017 [US6132851]
PA - GA-TEK Inc
ACT - 20031001 REASSIGNED
BILL OF SALE AND INSTRUMENT OF ASSIGNMENT AND
ASSUMPTION

Assignor: GOULD ELECTRONICS INC. DATE SIGNED: 09/30/2003

Assignee: NIKKO MATERIALS USA, INC. 125 NORTH PRICE ROAD
CHANDLER ARIZONA 85224

Reel 014022/Frame 0437

Contact: JONES DAY DEBRA L. PEJEAU 901 LAKESIDE AVENUE NORTH
POINT CLEVELAND, OH 44114

20031017 REISSUE REQUESTED
ISSUE DATE OF O.G.: 20031111
REISSUE REQUEST NUMBER: 10/617653
EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1774

Reissue Patent Number:

20031017 REISSUE REQUESTED
ISSUE DATE OF O.G.: 20031118
REISSUE REQUEST NUMBER: 10/659793
EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1774

Reissue Patent Number:

Search statement 2

Query/Command : FILE INPADOC

PLUSPAT - Time in minutes : 0,39
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Cost estimated for the last database search :	2.26 USD
Estimated total session cost :	2.85 USD

LGST - Time in minutes : 0,09
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Estimated cost :	0.11 USD
Records displayed and billed : 1	
Estimated cost :	0.60 USD
Legal-Status informations : 1	
Estimated cost :	0.50 USD
Cost estimated for the last database search :	1.21 USD
Estimated total session cost :	4.06 USD

CRXX - Time in minutes : 0,10
The cost estimation below is based on Questel's
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Estimated cost :	0.18 USD
Records displayed and billed : 1	
Estimated cost :	5.50 USD
Legal-Status informations : 1	
Estimated cost :	0.50 USD
Cost estimated for the last database search :	6.18 USD
Estimated total session cost :	10.24 USD

LITA - Time in minutes : 0,01
The cost estimation below is based on Questel's
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Estimated cost :	0.02 USD
Cost estimated for the last database search :	0.02 USD
Estimated total session cost :	10.26 USD

Selected file: INPADOC

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Search statement 1

Query/Command : FAM US6132851/PN

1 Patent Groups

**** SS 1: Results 5**

Search statement 2

Query/Command : FAMSTATE NONSTOP

1 / 5 INPADOC - ©INPADOC

PN - CN 1118367 A 19960313 [CN1118367]
TI - ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD
LAMINATES USING SAME
IN - POUTASSE CHARLES A [US]
PA - GOULD ELECTRONICS INC [US]
AP - CN 95107661/95-A 19950623 [1995CN-0107661]
PR - US 267877/94-A 19940628 [1994US-0267877]
IC - C09J-161/06; B32B-015/20

2 / 5 INPADOC - ©INPADOC

PN - EP 691389 A1 19960110 [EP-691389]
TI - ADHESIVE COMPOSITIONS AND COPPER FOIL AND COPPER CLAD
LAMINATES USING SAME
LA - ENG
IN - POUTASSE CHARLES A [US]
PA - GOULD ELECTRONICS INC [US]
AP - EP 95304380/95-A 19950622 [1995EP-0304380]
PR - US 267877/94-A 19940628 [1994US-0267877]
IC - C09J-163/00; C08L-063/00; H05K-003/38
DS - AT* DE* FR* GB* IT* LU*

1 / 1 LEGALI - ©EPO

PN - EP0691389 A1 19960110 [EP-691389]
AP - EP95304380 19950622 [1995EP-0304380]
ACTE - 19960110 EP/AK-A [+]
DESIGNATED CONTRACTING STATES:

AT DE FR GB IT LU

19960807 EP/17P-A [+]
REQUEST FOR EXAMINATION FILED
EFFECTIVE DATE: 19960611

20000517 EP/RAP1-A
APPLICANT REASSIGNMENT (CORRECTION)
OWNER: GA-TEK, INC. (DOING BUSINESS AS GOULD ELECTRONICS

20001011 EP/17Q-A [+]
FIRST EXAMINATION REPORT
EFFECTIVE DATE: 20000824

20020612 EP/18D-A [-]
DEEMED TO BE WITHDRAWN
EFFECTIVE DATE: 20011128

UP - 2003-22

3 / 5 INPADOC - ©INPADOC

PN - JP 8048960 A2 19960220 [JP08048960]
TI - ADHESIVE COMPOSITION, COPPER FOIL AND COPPER-CLAD
LAMINATE CONSISTING OF THEM
IN - CHIYAARUZU EI POOTATSUSE
PA - GOULD ELECTRONICS INC
AP - JP 162675/95-A 19950628 [1995JP-0162675]
PR - US 267877/94-A 19940628 [1994US-0267877]
IC - C09J-163/00; C08G-059/14; H05K-003/38; B32B-015/08

4 / 5 INPADOC - ©INPADOC

PN - TW 383333 B 20000301 [TW-383333]
TI - ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD
LAMINATES USING SAME
IN - POUTASSE CHARLES A [US]
PA - GOULD ELECTRONICS INC [US]
AP - TW 84103987/95-A 19950422 [1995TW-0103987]
PR - US 267877/94-A 19940628 [1994US-0267877]
IC - C09J-161/00; C09J-163/00

1 / 1 LEGALI - ©EPO

PN - TW383333 B 20000301 [TW-383333]
AP - TW84103987 19950422 [1995TW-0103987]
ACTE - 20000704 TW/GD4A-A [+]
ISSUE OF PATENT CERTIFICATE FOR GRANTED INVENTION PATENT

20040221 TW/MM4A-A [-]

ANNULMENT OR LAPSE OF PATENT DUE TO NON-PAYMENT OF FEES

UP - 2004-31

*5 / 5 INPADOC - ©INPADOC***PN** - US 6132851 A 20001017 [US6132851]**TI** - ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD LAMINATES USING SAME**IN** - POUTASSE CHARLES A [US]**PA** - GA TEK INC [US]**AP** - US 267877/94-A 19940628 [1994US-0267877]**PR** - US 267877/94-A 19940628 [1994US-0267877]**IC** - B32B-003/00

*1 / 1 LEGALI - ©EPO***PN** - US6132851 A 20001017 [US6132851]**AP** - US26787794 19940628 [1994US-0267877]**ACTE** - 20000522 US/AS-A

ASSIGNMENT

OWNER: GA-TEK INC. 34929 CURTIS BOULEVARD EASTLAKE OHIO 4;

EFFECTIVE DATE: 19971030

CHANGE OF NAME;ASSIGNOR:GOULD ELECTRONICS,

INC.;REEL/FRAME:010923/0373

20031111 US/RF-A

REISSUE APPLICATION FILED

EFFECTIVE DATE: 20021017

20031118 US/RF-A

REISSUE APPLICATION FILED

EFFECTIVE DATE: 20021017

UP - 2004-29

Search statement 2

PATNO IS 6132851

DATE: SEPTEMBER 10, 2004
LIBRARY: PATENT
FILE: ALL

Your search request is:
PATNO IS 6132851

Number of PATENTS found with your search request through:
LEVEL 1... 1

Your search request has found 1 PATENT through Level 1.
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For further explanation, press the H key (for HELP) and then the ENTER key.

LEVEL 1 - 1 PATENT

1. 6132851 , October 17, 2000 , Adhesive compositions and copper foils and copper clad laminates using same, Poutasse, Charles A. - Cleveland, Ohio, United States (US), 267877 (08), GA-TEK Inc., Eastlake, Ohio, United States (US), 02, June 28, 1994 - ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS) ., GOULD ELECTRONICS INC. 35129 CURTIS BOULEVARD EASTLAKE, OH 44095-4001, Reel and Frame Number: 007071/0747 May 22, 2000 - CHANGE OF NAME (SEE DOCUMENT FOR DETAILS)., GA-TEK INC. 34929 CURTIS BOULEVARD EASTLAKE OHIO 44095, Reel and Frame Number: 010923/0373 October 1, 2003 - BILL OF SALE AND INSTRUMENT OF ASSIGNMENT AND ASSUMPTION, NIKKO MATERIALS USA, INC. 125 NORTH PRICE ROAD CHANDLER ARIZONA 85224, Reel and Frame Number: 014022/0437

CORE TERMS: foil, sup, sub, adhesive, composition, copper, layer, epoxy, resin, substrate ...

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6132851

October 17, 2000

Adhesive compositions and copper foils and copper clad
laminates using same

REISSUE: October 17, 2002 - Reissue Application filed Ex. Gp.: 1774; Re. S.N.
10/617,653 (O.G. November 11, 2003)

October 17, 2002 - Reissue Application filed Ex. Gp.: 1774; Re. S.N. 10/659,793
(O.G. November 18, 2003)

APPL-NO: 267877 (08)

FILED-DATE: June 28, 1994

GRANTED-DATE: October 17, 2000

CORE TERMS: foil, sup, sub, adhesive, composition, copper, layer, epoxy, resin,
substrate ...

6132851 OR 6,132,851

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